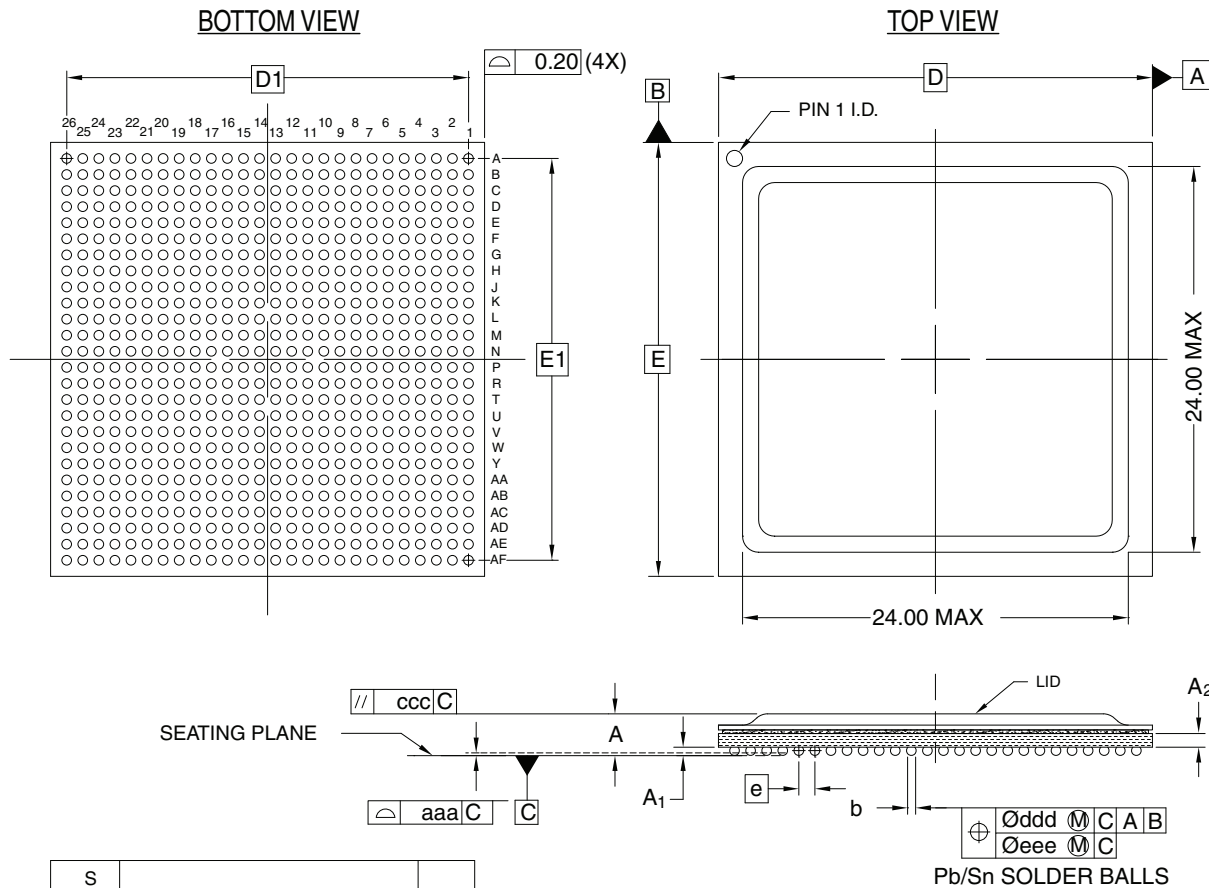













# 676 Ball Flip-Chip BGA (EF676) Package



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.35		3.00	
A <sub>1</sub>	0.40		0.60	
A <sub>2</sub>	0.65		1.10	
D/E	27.00 BASIC			
D <sub>1</sub> /E <sub>1</sub>	25.00 REF			
e	1.00 BASIC			
Øb	0.50	0.60	0.70	
aaa			0.20	
ccc			0.25	
ddd			0.25	
eee			0.10	
M	26			

## NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE
3. CONFORMS TO JEDEC MS-034-AAL-1

PK375\_01\_051409

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
05/26/09	1.0	Initial Xilinx release.

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